

WHAT IS CLAIMED IS:

1. A method of making a device comprising:  
winding a coil;  
disposing the coil in a predetermined position on a component which forms part of the device;  
connecting the ends of the coil to first and second pins by winding the ends of the coil onto the pins; and  
disposing the first and second pins in electrical connection with first and second connection structures formed on a PCB (printed circuit board) which is disposed on the component.
2. A method as set forth in claim 1, wherein a first end of a wire which is used form the coil is wound onto the first pin before the wire is wound into the coil.
3. A method as set forth in claim 1, wherein the component is molded body and wherein the steps of disposing the coil, connecting the ends of the coil to the first and second pins and the step of disposing the first and second pins in the first and second connection structure, are all carried out in the absence of overmolding of any part of the coil once disposed on the molded body.
4. A method as set forth in claim 1, further comprising soldering the ends of the coils to the pins.
5. A method as set forth in claim 4, soldering the pins to the connection structures of the PCB.
6. A method as set forth in claim 5, wherein the step of soldering the ends of the coils to the pins and the step of soldering the pins to the connection structures on the PCB are carried out after the ends of the coil have been wound on the pins and the pins have been disposed in position with respect to the PCB so that the pins are in contact with the connection sites.

7. A method as set forth in claim 1, wherein the step of winding the coil comprises winding the coil on a bobbin which is separate from the component.
8. A method as set forth in claim 1, wherein the molded body is adapted for use in a vehicle
9. A method as set forth in claim 8, wherein the vehicle is an automotive vehicle.
10. A method of making a device comprising:
  - winding a coil;
  - connecting a first end of the coil to a first pin;
  - disposing the coil in a predetermined position on a component which forms part of the device;
  - connecting a second end of the coil to a second pin;
  - disposing the first pin in a first predetermined connection position on a PCB (printed circuit board) which is disposed in the device with the component; and
  - disposing the second pin a second predetermined connection position on the PCB.
11. A method as set forth in claim 10, wherein the step of winding the coil is carried out on a form and is disposed on the device and wherein the steps of connecting the first end of the coil to the first pin; connecting the second end of the coil to the second pin, disposing the first pin in the predetermined connection position and the step of disposing the second pin in the second predetermined connection position are carried out in the absence of a molding process wherein the coil is overmolded.
12. A method as set forth in claim 11, wherein the form is a bobbin.
13. A method as set forth in claim 10, wherein the steps of connecting the ends of the coil to the first and second pins by winding the ends of the coil onto the first and second pins; and disposing the first and second pins in the connection positions further

comprises soldering the first and second coil ends to the first and second pins and soldering the first and second pins to electrical connection structures associated with the first and second connection positions.

14. A method as set forth in claim 10, wherein the soldering of the first and second coil ends to the first and second pins and the soldering of the first and second pins to the first and second connection sites are all carried out while the pins are *in situ* in the first and second connection sites.

15. A method of making a device comprising:  
molding first and second components;  
forming an antenna coil;  
disposing the antenna coil on the first component; and without overmolding the coil:  
disposing a PCB on one of the first and second components;  
connecting first and second ends of the coil to the PCB to establish first and second electrical connections between the coil and the PCB; and  
coupling the first and second components together to enclose the non-overmolded coil.

16. A method as set forth in claim 15, wherein the step of connecting the first and second ends of the coil to the PCB comprises:  
winding a first end of the coil on a first pin;  
winding a second end of the coil on a second pin;  
disposing the first pin in a first predetermined position on the PCB;  
disposing the second pin in a second predetermined position on the PCB;  
soldering the first end of the coil to the first pin;  
soldering the second end of the coil to the second pin;  
soldering the first pin to a first connection structure on the PCB; and  
soldering the second pin to a second connection structure on the PCB.

17. A device comprising:
  - first and second molded components;
  - a non-overmolded antenna coil which is disposed on one of the first and second molded components;
  - a PCB which is disposed with one of the first and second molded components and is connected to the antenna coil via first and second pins which respectively have first and second ends of the coil wound therearound and soldered thereto, and wherein the first and second pins are soldered to first and second connection structures on the PCB.
18. A device as set forth in claim 17, wherein the first and second molded components couple together to enclose the non-overmolded antenna coil.
19. A device as set forth in claim 18, wherein the PCB is enclosed by the intercoupled first and second molded components.
20. A device as set forth in claim 17, wherein the device comprises an antitheft device for an automotive vehicle.